

# TLE8250G

High Speed CAN-Transceiver

## Data Sheet

Rev. 1.0, 2010-06-02

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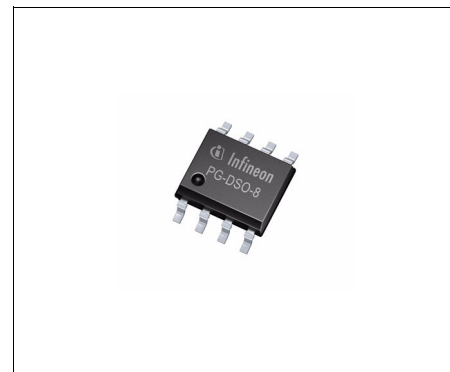
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## 1 Overview

### Features

- Fully compatible to ISO 11898-2
- Wide common mode range for electromagnetic immunity (EMI)
- Very low electromagnetic emission (EME)
- Excellent ESD robustness
- CAN Short-Circuit-proof to ground, battery and  $V_{CC}$
- TxD time-out function
- Low CAN bus leakage current in Power Down mode
- Over temperature protection
- Protected against automotive transients
- CAN data transmission rate up to 1 Mbaud
- Green Product (RoHS compliant)
- AEC Qualified



**PG-DSO-8**

### Description

The TLE8250G is a transceiver designed for CAN networks in automotive and industrial applications. As an interface between the physical bus layer and the CAN protocol controller, the TLE8250G drives the signals to the bus and protects the microcontroller against disturbances coming from the network. Based on the high symmetry of the CANH and CANL signals, the TLE8250G provides a very low level of electromagnetic emission (EME) within a broad frequency range. The TLE8250G is integrated in a RoHS complaint PG-DSO-8 package and fulfills or exceeds the requirements of the ISO11898-2.

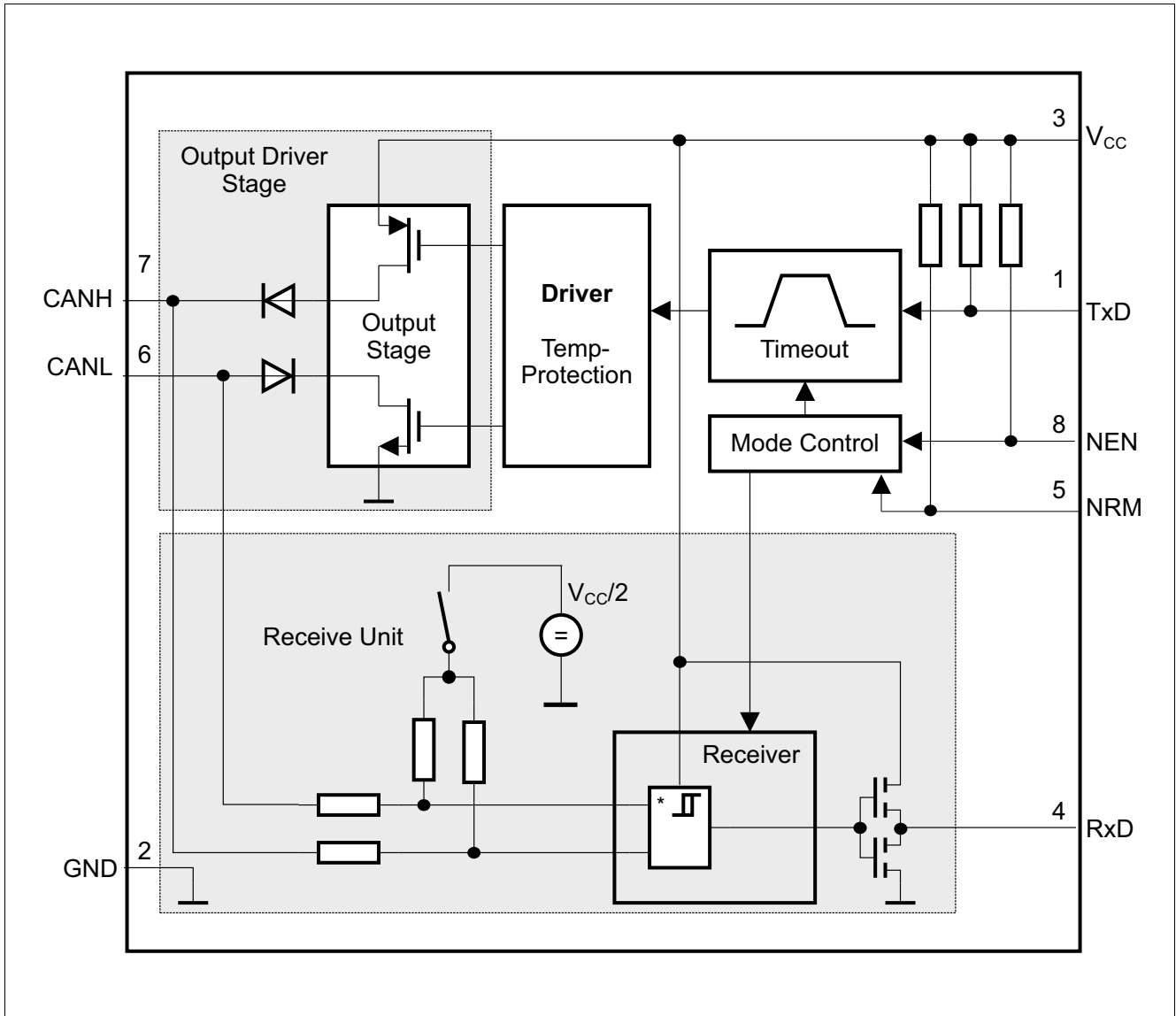
As a successor to the first generation of HS CAN transceivers, the TLE8250G is fully pin and function compatible to his predecessor model the TLE6250G. The TLE8250G is optimized to provide an excellent passive behavior in Power Down mode. This feature makes the TLE8250G extremely suitable for mixed supply HS CAN networks.

Based on the Infineon Smart Power Technology SPT<sup>®</sup>, the TLE8250G provides industry leading ESD robustness together with a very high electromagnetic immunity (EMI). The Infineon Smart Power Technology SPT<sup>®</sup> allows bipolar and CMOS control circuitry in accordance with DMOS power devices to exist on the same monolithic circuit. The TLE8250G and the Infineon SPT<sup>®</sup> technology are AEC qualified and tailored to withstand the harsh conditions of the Automotive Environment.

Three different operation modes, additional Fail Safe features like a TxD time-out and the optimized output slew rates on the CANH and CANL signals are making the TLE8250G the ideal choice for large CAN networks with high data rates.

Type	Package	Marking
TLE8250G	PG-DSO-8	8250G

## 2 Block Diagram



**Figure 1** Block Diagram

*Note: In comparison to the TLE6250G the pin 8 (INH) was renamed to the term NEN, the function remains unchanged. NEN stands for Not ENable. The naming of the pin 5 changed from RM (TLE6250G) to NRM on the TLE8250G. The function of pin 5 remains unchanged.*

### 3 Pin Configuration

#### 3.1 Pin Assignment

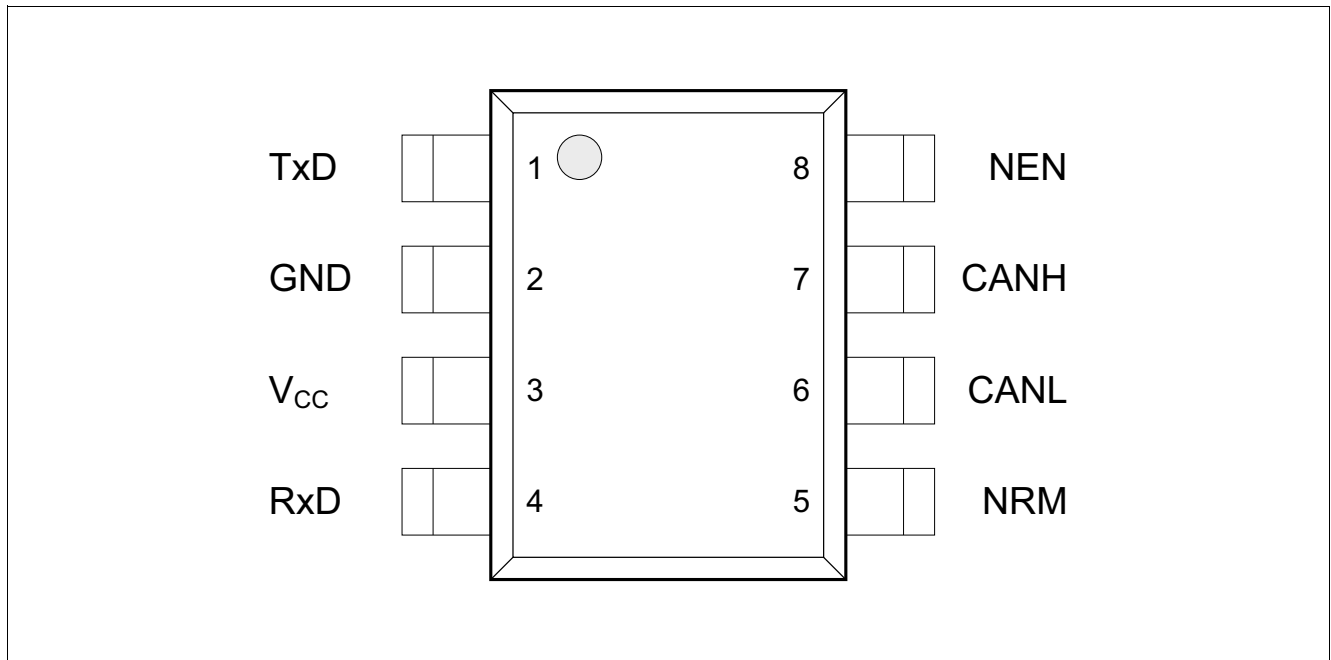


Figure 2 Pin Configuration

#### 3.2 Pin Definitions and Functions

Table 1 Pin Definition and Functions

Pin	Symbol	Function
1	TxD	<b>Transmit Data Input;</b> internal pull-up to $V_{CC}$ , “Low” for “Dominant” state.
2	GND	<b>Ground</b>
3	$V_{CC}$	<b>Transceiver Supply Voltage;</b> 100 nF decoupling capacitor to GND required.
4	RxD	<b>Receive Data Output;</b> “Low” in “Dominant” state.
5	NRM	<b>Receive-Only Mode input<sup>1)</sup>;</b> Control input for selecting the Receive-Only mode, internal pull-up to $V_{CC}$ , “Low” to select the Receive-Only mode.
6	CANL	<b>CAN Bus Low level I/O;</b> “Low “ in “Dominant” state.
7	CANH	<b>CAN Bus High level I/O;</b> “High “ in “Dominant” state.
8	NEN	<b>Not ENable Input<sup>1)</sup>;</b> internal pull-up to $V_{CC}$ , “Low” to select Normal Operation mode or Receive-Only mode.

1) The naming of pin 8 and pin 5 are different between the TLE8250G and its forerunner model the TLE6250G. The function of pin 8 and pin 5 remains the same.

## 4 Functional Description

CAN is a serial bus system that connects microcontrollers, sensor and actuators for real-time control applications. The usage of the **C**ontrol **A**rea **N**etwork (abbreviated CAN) within road vehicles is described by the international standard ISO 11898. According to the 7 layer OSI reference model the physical layer of a CAN bus system specifies the data transmission from one CAN node to all other available CAN nodes inside the network. The physical layer specification of a CAN bus system includes all electrical and mechanical specifications of a CAN network. The CAN transceiver is part of the physical layer specification. Several different physical layer definitions of a CAN network have been developed over the last years. The TLE8250G is a High Speed CAN transceiver without any dedicated Wake-Up function. High Speed CAN Transceivers without Wake-Up function are defined by the international standard ISO 11898-2.

### 4.1 High Speed CAN Physical Layer

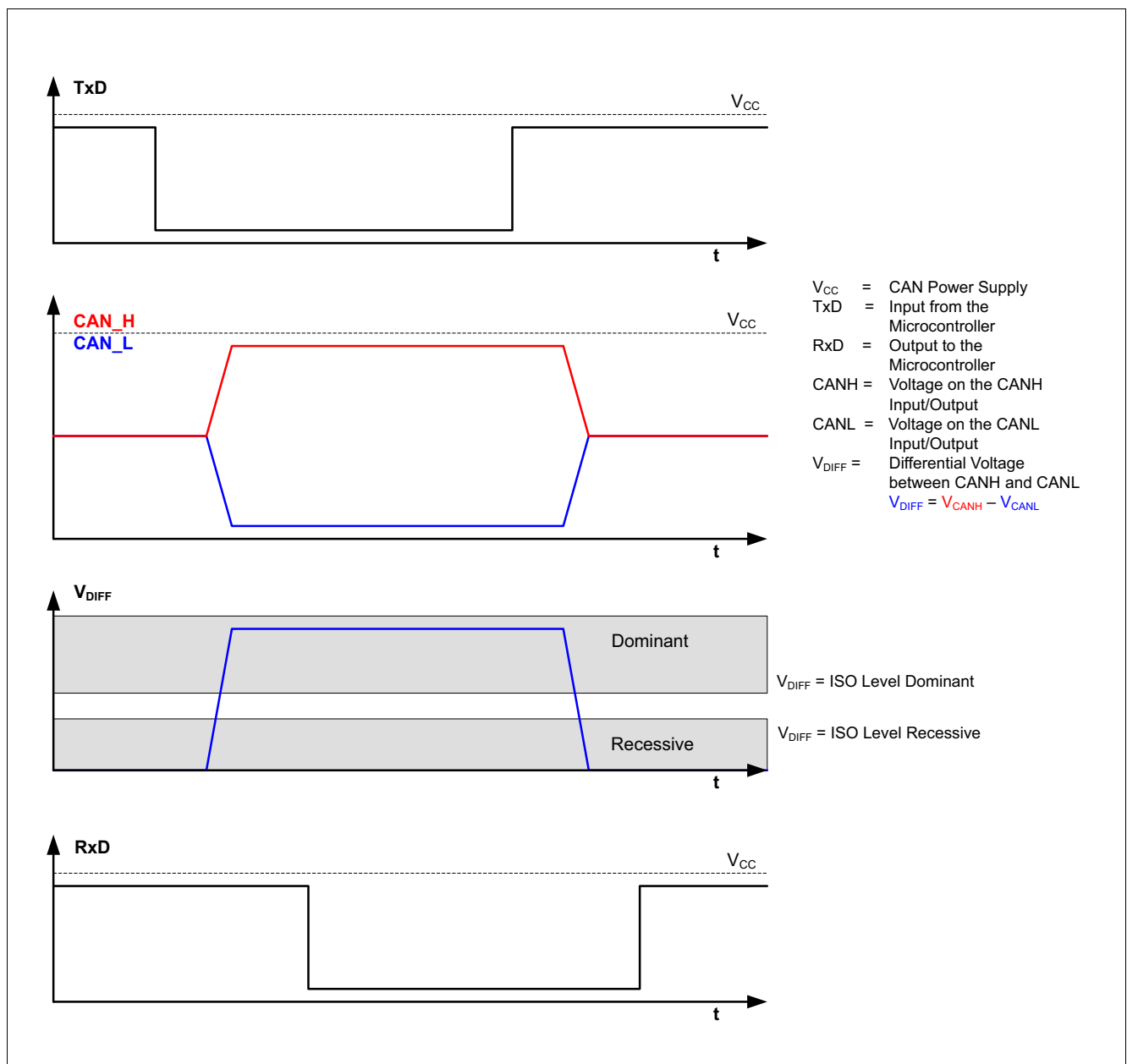


Figure 3 High Speed CAN Bus Signals and Logic Signals

The TLE8250G is a High Speed CAN transceiver, operating as an interface between the CAN controller and the physical bus medium. A HS CAN network is a two wire, differential network which allows data transmission rates up to 1 MBaud. Characteristic for a HS CAN network are the two signal states on the CAN bus: “Dominant” and “Recessive” (see [Figure 3](#)).

The pins CANH and CANL are the interface to the CAN bus and both pins operate as an input and as an output. The pins RxD and TxD are the interface to the microcontroller. The pin TxD is the serial data input from the CAN controller, the pin RxD is the serial data output to the CAN controller. As shown in [Figure 1](#), the HS CAN transceiver TLE8250G has a receive and a transmit unit, allowing the transceiver to send data to the bus medium and monitor the data from the bus medium at the same time. The HS CAN transceiver TLE8250G converts the serial data stream available on the transmit data input TxD, into a differential output signal on CAN bus, provided by the pins CANH and CANL. The receiver stage of the TLE8250G monitors the data on the CAN bus and converts them to a serial, single ended signal on the RxD output pin. A logical “Low” signal on the TxD pin creates a “Dominant” signal on the CAN bus, followed by a logical “Low” signal on the RxD pin (see [Figure 3](#)). The feature, broadcasting data to the CAN bus and listening to the data traffic on the CAN bus simultaneous is essential to support the bit to bit arbitration inside CAN networks.

The voltage levels for HS CAN transceivers are defined by the ISO 11898-2 and the ISO 11898-5 standards. If a data bit is “Dominant” or “Recessive” depends on the voltage difference between pins CANH and CANL:

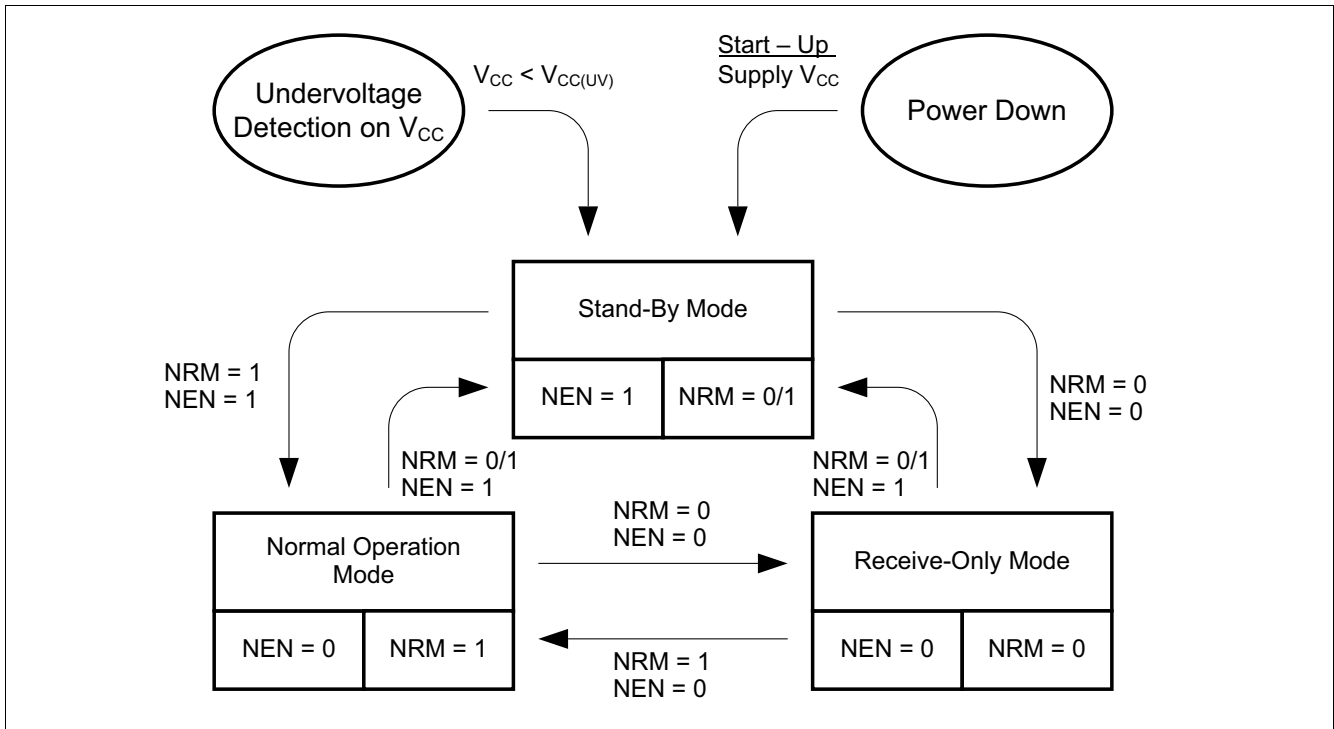
$$V_{\text{DIFF}} = V_{\text{CANH}} - V_{\text{CANL}}$$

In comparison to other differential network protocols the differential signal on a CAN network can only be larger or equal to 0 V. To transmit a “Dominant” signal to the CAN bus the differential signal  $V_{\text{DIFF}}$  is larger or equal to 1.5 V. To receive a “Recessive” signal from the CAN bus the differential  $V_{\text{DIFF}}$  is smaller or equal to 0.5 V.

Partially supplied CAN networks are networks where the CAN bus participants have different power supply conditions. Some nodes are connected to the power supply, some other nodes are disconnected from the power supply. Regardless, if the CAN bus participant is supplied or not supplied, each participant connected to the common bus media must not disturb the communication. The TLE8250G is designed to support partially supplied networks. In Power Down mode, the receiver input resistors are switched off and the transceiver input is high resistive.

## 4.2 Operation Modes

Three different operation modes are available on TLE8250G. Each mode with specific characteristics in terms of quiescent current or data transmission. For the mode selection the digital input pins NEN and NRM are used. **Figure 4** illustrates the different mode changes depending on the status of the NEN and NRM pins. After supplying  $V_{CC}$  to the HS CAN transceiver, the TLE8250G starts in Stand-By mode. The internal pull-up resistors are setting the TLE8250G to Stand-By per default. If the microcontroller is up and running the TLE8250G can change to any operation mode within the time for mode change  $t_{Mode}$ .



**Figure 4** Operation Modes

The TLE8250G has 3 major operation modes:

- Stand-By mode
- Normal Operation mode
- Receive-Only mode

**Table 2** Operating modes

Mode	NRM	NEN	Bus Bias	Comments
Normal Operation	“High”	“Low”	$V_{CC}/2$	Output driver stage is active. Receiver unit is active.
Stand-By	“Low” or “High”	“High”	Floating	Output driver stage is disabled. Receiver unit is disabled.
Receive-Only	“Low”	“Low”	$V_{CC}/2$	Output driver stage is disabled. Receiver unit is active.
$V_{CC}$ off	“Low” or “High”	“Low” or “High”	Floating	Output driver stage is disabled. Receiver unit is disabled.



### 4.3 Normal Operation Mode

In Normal Operation mode the HS CAN transceiver TLE8250G sends the serial data stream on the TxD pin to the CAN bus while at the same time the data available on the CAN bus are monitored to the RxD pin. In Normal Operation mode all functions of the TLE8250G are active:

- The output driver stage is active and drives data from the TxD to the CAN bus.
- The receiver unit is active and provides the data from the CAN bus to the RxD pin.
- The bus basing is set to  $V_{CC}/2$ .
- The under-voltage monitoring on the power supply  $V_{CC}$  is active.

To enter the Normal Operation mode set the pin NRM to logical “High” and the pin NEN to logical “Low” (see [Table 2](#) or [Figure 4](#)). Both pins, the NEN pin and the NRM pin have internal pull-up resistors to the power-supply  $V_{CC}$ .

### 4.4 Receive-Only Mode

The Receive-Only mode can be used to test the connection of the bus medium. The TLE8250G can still receive data from the bus, but the output driver stage is disabled and therefore no data can be sent to the CAN bus. All other functions are active:

- The output driver stage is disabled and data which are available on the TxD pin are blocked and not send to the CAN bus.
- The receiver unit is active and provides the data from the CAN bus to the RxD output pin.
- The bus basing is set to  $V_{CC}/2$ .
- The under-voltage monitoring on the power supply  $V_{CC}$  is active.

To enter the Receive-Only mode set the pin NRM to logical “Low” and the pin NEN to logical “Low” (see [Table 2](#) or [Figure 4](#)). In case the Receive-Only mode will not be used, the NRM pin can be left open.

### 4.5 Stand-By Mode

Stand-By mode is an idle mode of the TLE8250G with optimized power consumption. In Stand-By mode the TLE8250G can not send or receive any data. The output driver stage and the receiver unit are disabled. Both CAN bus pins, CANH and CANL are floating.

- The output driver stage is disabled.
- The receiver unit is disabled.
- The bus basing is floating.
- The under-voltage monitoring on the power supply  $V_{CC}$  is active.

To enter the Stand-By mode set the pin NEN to logical “High”, the logical state of the NRM pin has no influence for the mode selection (see [Table 2](#) or [Figure 4](#)). Both pins the NEN and the NRM pin have an internal pull-up resistor to the power-supply  $V_{CC}$ . If the Stand-By mode is not used in the application, the NEN pin needs to get connected to GND.

In case the NRM pin is set to logical “Low” in Stand-By mode, the internal pull-up resistor causes an additional quiescent current from  $V_{CC}$  to GND, therefore it is recommended to set the NRM pin to logical “High” in Stand-By mode or leave the pin open if the Receive-Only mode is not used in the application.

### 4.6 Power Down Mode

Power Down mode means the TLE8250G is not supplied. In Power Down the differential input resistors of the receiver stage are switched off. The CANH and CANL bus interface of the TLE8250G acts as an high impedance input with a very small leakage current. The high ohmic input doesn't influence the “Recessive” level of the CAN network and allows an optimized EME performance of the whole CAN network.

## 5 Fail Safe Functions

### 5.1 Short circuit protection

The CANH and CANL bus outputs are short-circuit-proof, either against GND or a positive supply voltage. A current limiting circuit protects the transceiver against damages. If the device is heating up due to a continuous short on CANH or CANL, the internal over-temperature protection switches off the bus transmitter.

### 5.2 Open Logic Pins

All logic input pins have internal pull-up resistor to  $V_{CC}$ . In case the  $V_{CC}$  supply is activated and the logical pins are open or floating, the TLE8250G enters into the Stand-By mode per default. In Stand-By mode the output driver stage of the TLE8250G is disabled, the bus biasing is shut off and the HS CAN transceiver TLE8250G will not influence the data on the CAN bus.

### 5.3 TxD Time-Out function

The TxD Time-out feature protects the CAN bus against permanent blocking in case the logical signal on the TxD pin is continuously “Low”. A continuous “Low” signal on the TxD pin can have it’s root cause in a locked-up microcontroller or in a short on the printed circuit board for example. In Normal Operation mode, a logical “Low” signal on the TxD pin for the time  $t > t_{TxD}$  the TLE8250G activates the TxD Time-out and the TLE8250G disables the output driver stage (see [Figure 5](#)). The receive unit is still active and the data on the bus are monitored at the RxD output pin.

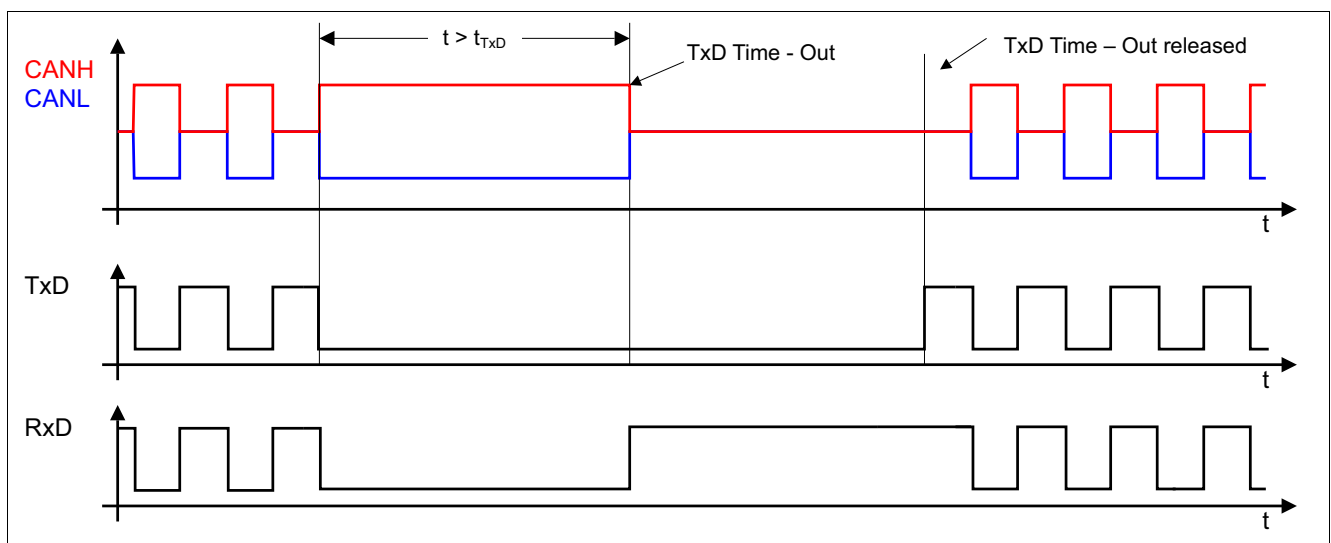


Figure 5 TxD Time-Out function

[Figure 5](#) shows how the output driver stage is deactivated and activated again. A permanent “Low” signal on the TxD input pin activates the TxD time-out function and deactivates the output driver stage. To release the output driver stage after a TxD time-out event the TLE8250G requires a signal change on the TxD input pin from logical “Low” to logical “High”.

### 5.4 Under-Voltage detection

The HS CAN Transceiver TLE8250G is equipped with an under-voltage detection on the power supply  $V_{CC}$ . In case of an under-voltage event on  $V_{CC}$ , the under-voltage detection changes the operation mode of TLE8250G to the Stand-By mode, regardless of the logical signal on the pins NEN and NRM (see [Figure 6](#)). If the transceiver TLE8250G recovers from the under-voltage event, the operation mode returns to the programmed mode by the logical pins NEN and NRM.

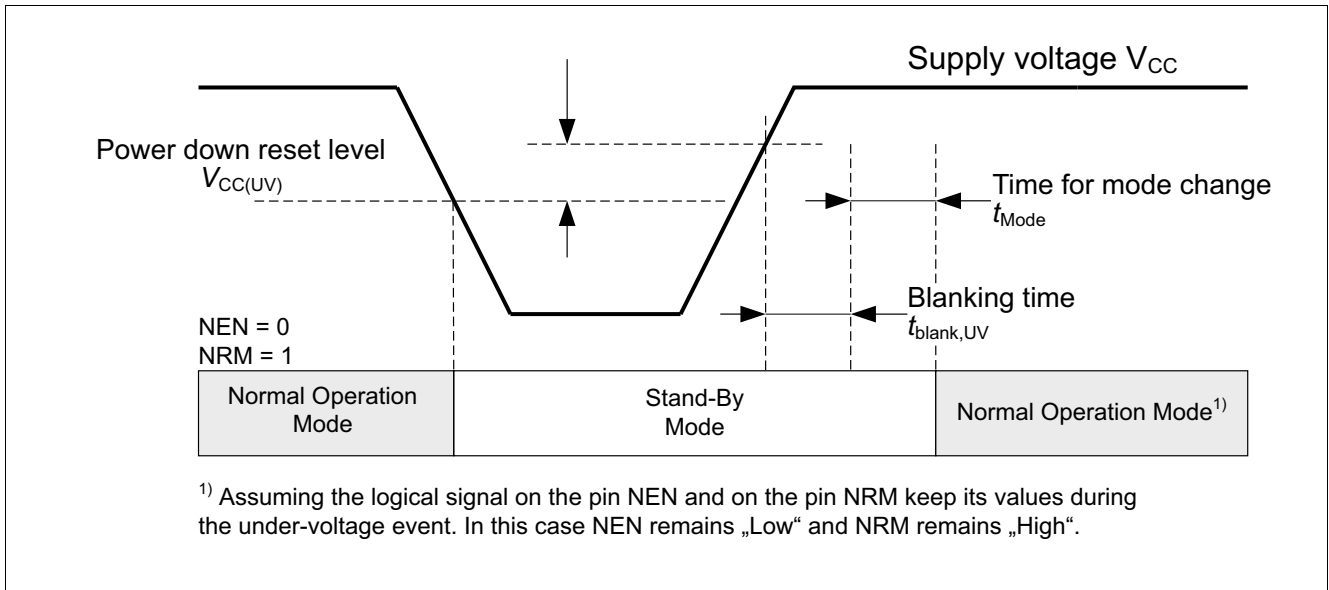


Figure 6 Under-Voltage detection on  $V_{CC}$

### 5.5 Over-Temperature protection

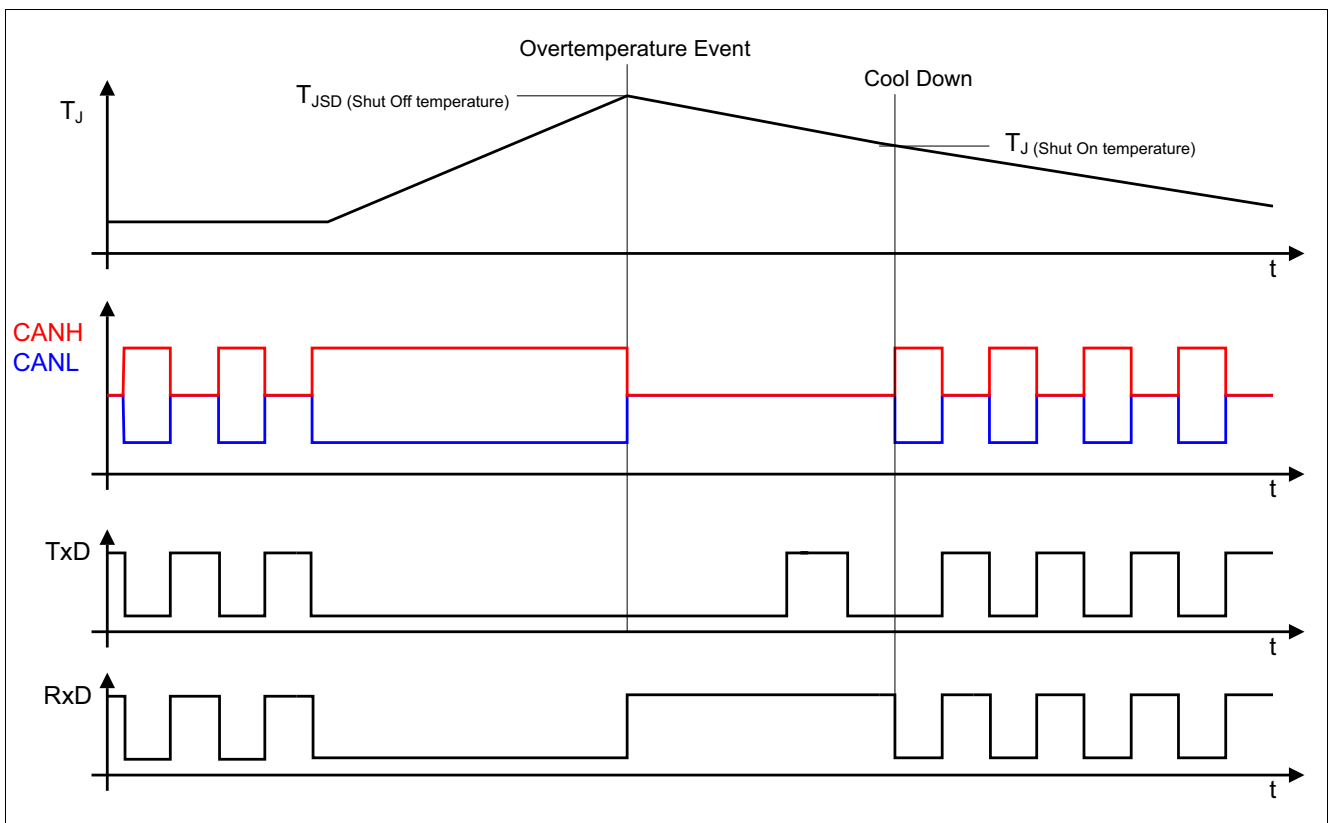


Figure 7 Over-Temperature protection

The TLE8250G has an integrated over-temperature detection to protect the device against thermal overstress of the output driver stage. In case of an over-temperature event, the temperature sensor will disable the output driver stage (see [Figure 1](#)). After the device cools down the output driver stage is activated again (see [Figure 7](#)). Inside the temperature sensor a hysteresis is implemented.

## 6 General Product Characteristics

### 6.1 Absolute Maximum Ratings

**Table 3 Absolute Maximum Ratings Voltages, Currents and Temperatures<sup>1)</sup>**

All voltages with respect to ground; positive current flowing into pin;  
(unless otherwise specified)

Pos.	Parameter	Symbol	Limit Values		Unit	Remarks
			Min.	Max.		
<b>Voltages</b>						
6.1.1	Supply voltage	$V_{CC}$	-0.3	6.0	V	–
6.1.2	CANH DC voltage versus GND	$V_{CANH}$	-40	40	V	–
6.1.3	CANL DC voltage versus GND	$V_{CANL}$	-40	40	V	–
6.1.4	Differential voltage between CANH and CANL	$V_{CAN\ diff}$	-40	40	V	
6.1.5	Logic voltages at NEN, NRM, TxD, RxD	$V_I$	-0.3	6.0	V	–
<b>Temperatures</b>						
6.1.6	Junction temperature	$T_j$	-40	150	°C	–
6.1.7	Storage temperature	$T_S$	- 55	150	°C	–
<b>ESD Resistivity</b>						
6.1.8	ESD Resistivity at CANH, CANL versus GND	$V_{ESD}$	-8	8	kV	Human Body Model (100pF via 1.5 kΩ) <sup>2)</sup>
6.1.9	ESD Resistivity all other pins	$V_{ESD}$	-2	2	kV	Human Body Model (100pF via 1.5 kΩ) <sup>2)</sup>

1) Not subject to production test, specified by design

2) ESD susceptibility HBM according to EIA / JESD 22-A 114

*Note: Within the functional range the IC operates as described in the circuit description. The electrical characteristics are specified within the conditions given in the related electrical characteristics table.*

## 6.2 Functional Range

**Table 4 Operating Range**

Pos.	Parameter	Symbol	Limit Values		Unit	Conditions
			Min.	Max.		
<b>Supply Voltages</b>						
6.2.1	Transceiver Supply Voltage	$V_{CC}$	4.75	5.25	V	–
<b>Thermal Parameters</b>						
6.2.2	Junction temperature	$T_J$	-40	150	°C	<sup>1)</sup>

1) Not subject to production test, specified by design

*Note: Within the functional range the IC operates as described in the circuit description. The electrical characteristics are specified within the conditions given in the related electrical characteristics table.*

## 6.3 Thermal Characteristics

*Note: This thermal data was generated in accordance with JEDEC JESD51 standards. For more information, go to [www.jedec.org](http://www.jedec.org).*

**Table 5 Thermal Resistance<sup>1)</sup>**

Pos.	Parameter	Symbol	Limit Values			Unit	Remarks
			Min.	Typ.	Max.		
<b>Thermal Resistance</b>							
6.3.1	Junction to Ambient <sup>1)</sup>	$R_{thJA}$	–	130	–	K/W	<sup>2)</sup>
<b>Thermal Shutdown Junction Temperature</b>							
6.3.2	Thermal shutdown temp.	$T_{JSD}$	150	175	200	°C	–
6.3.3	Thermal shutdown hysteresis	$\Delta T$	–	10	–	K	–

1) Not subject to production test, specified by design

2) Specified  $R_{thJA}$  value is according to Jedec JESD51-2,-7 at natural convection on FR4 2s2p board; The Product (TLE8250G) was simulated on a 76.2 x 114.3 x 1.5 mm board with 2 inner copper layers (2 x 70µm Cu, 2 x 35µm Cu).

## 7 Electrical Characteristics

### 7.1 Functional Device Characteristics

**Table 6 Electrical Characteristics**

4.75 V <  $V_{CC}$  < 5.25 V;  $R_L = 60 \Omega$ ;  $T_j = -40 \text{ }^\circ\text{C}$  to  $+150 \text{ }^\circ\text{C}$ ; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Pos.	Parameter	Symbol	Limit Values			Unit	Remarks
			Min.	Typ.	Max.		
<b>Current Consumption</b>							
7.1.1	Current consumption	$I_{CC}$	–	6	10	mA	“Recessive” state; $V_{TxD} = V_{CC}$
7.1.2	Current consumption	$I_{CC}$	–	45	70	mA	“Dominant” state; $V_{TxD} = 0 \text{ V}$
7.1.3	Current consumption	$I_{CC(ROM)}$	–	6	10	mA	Receive-Only mode NRM = “Low”
7.1.4	Current consumption	$I_{CC(STB)}$	–	7	15	$\mu\text{A}$	Stand-By mode; TxD = NRM = “High”
<b>Supply Resets</b>							
7.1.5	$V_{CC}$ under-voltage monitor	$V_{CC(UV)}$	1.3	3.2	4.3	V	–
7.1.6	$V_{CC}$ under-voltage monitor hysteresis	$V_{CC(UV,H)}$	–	200	–	mV	<sup>1)</sup>
7.1.7	$V_{CC}$ under-voltage blanking time	$t_{blank(UV)}$	–	15	–	$\mu\text{s}$	<sup>1)</sup>
<b>Receiver Output: RxD</b>							
7.1.8	HIGH level output current	$I_{RD,H}$	–	-4	-2	mA	$V_{RxD} = 0.8 \times V_{CC}$ $V_{DIFF} < 0.5 \text{ V}$
7.1.9	LOW level output current	$I_{RD,L}$	2	4	–	mA	$V_{RxD} = 0.2 \times V_{CC}$ $V_{DIFF} > 0.9 \text{ V}$
<b>Transmission Input: TxD</b>							
7.1.10	HIGH level input voltage threshold	$V_{TD,H}$	–	$0.5 \times V_{CC}$	$0.7 \times V_{CC}$	V	“Recessive” state
7.1.11	LOW level input voltage threshold	$V_{TD,L}$	$0.3 \times V_{CC}$	$0.4 \times V_{CC}$	–	V	“Dominant” state
7.1.12	TxD pull-up resistance	$R_{TD}$	10	25	50	$\text{k}\Omega$	–
7.1.13	TxD input hysteresis	$V_{HYS(TxD)}$	–	200	–	mV	<sup>1)</sup>
7.1.14	TxD permanent dominant disable time	$t_{TxD}$	0.3	–	1.0	ms	–
<b>Not Enable Input NEN</b>							
7.1.15	HIGH level input voltage threshold	$V_{NEN,H}$	–	$0.5 \times V_{CC}$	$0.7 \times V_{CC}$	V	Stand-By mode;
7.1.16	LOW level input voltage threshold	$V_{NEN,L}$	$0.3 \times V_{CC}$	$0.4 \times V_{CC}$	–	V	Normal Operation mode;
7.1.17	NEN pull-up resistance	$R_{NEN}$	10	25	50	$\text{k}\Omega$	–
7.1.18	NEN input hysteresis	$V_{HYS(NEN)}$	–	200	–	mV	<sup>1)</sup>

**Electrical Characteristics**
**Table 6 Electrical Characteristics (cont'd)**

4.75 V <  $V_{CC}$  < 5.25 V;  $R_L = 60 \Omega$ ;  $T_j = -40 \text{ }^\circ\text{C}$  to  $+150 \text{ }^\circ\text{C}$ ; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Pos.	Parameter	Symbol	Limit Values			Unit	Remarks
			Min.	Typ.	Max.		
<b>Receive only Input NRM</b>							
7.1.19	HIGH level input voltage threshold	$V_{NRM,H}$	–	$0.5 \times V_{CC}$	$0.7 \times V_{CC}$	V	Normal Operation mode
7.1.20	LOW level input voltage threshold	$V_{NRM,L}$	$0.3 \times V_{CC}$	$0.4 \times V_{CC}$	–	V	Receive-Only mode
7.1.21	NRM pull-up resistance	$R_{NRM}$	10	25	50	k $\Omega$	–
7.1.22	NRM input hysteresis	$V_{NRM(Hys)}$	–	200	–	mV	<sup>1)</sup> –
<b>Bus Receiver</b>							
7.1.23	Differential receiver threshold “Dominant”	$V_{DIFF,(D)}$	–	0.75	0.9	V	Normal Operation mode
7.1.24	Differential receiver threshold “Recessive”	$V_{DIFF,(R)}$	0.5	0.6	–		Normal Operation mode
7.1.25	Differential receiver input range - “Dominant”	$V_{diff,rdN}$	0.9	–	5.0	V	Normal Operation mode
7.1.26	Differential receiver input range - “Recessive”	$V_{diff,drN}$	-1.0	–	0.5	V	Normal Operation mode
7.1.27	Common Mode Range	CMR	-12	–	12	V	$V_{CC} = 5 \text{ V}$
7.1.28	Differential receiver hysteresis	$V_{diff,hys}$	–	100	–	mV	<sup>1)</sup> –
7.1.29	CANH, CANL input resistance	$R_i$	10	20	30	k $\Omega$	“Recessive” state
7.1.30	Differential input resistance	$R_{diff}$	20	40	60	k $\Omega$	“Recessive” state
<b>Bus Transmitter</b>							
7.1.31	CANL/CANH recessive output voltage	$V_{CANL/H}$	2.0	2.5	3.0	V	$V_{TxD} = V_{CC}$ ; no load
7.1.32	CANH, CANL recessive output voltage difference	$V_{diff}$	-500	–	50	mV	$V_{TxD} = V_{CC}$ ; no load
7.1.33	CANL dominant output voltage	$V_{CANL}$	0.5	–	2.25	V	$V_{TxD} = 0 \text{ V}$ ; $50 \Omega < R_L < 65 \Omega$
7.1.34	CANH dominant output voltage	$V_{CANH}$	2.75	–	4.5	V	$V_{TxD} = 0 \text{ V}$ ; $50 \Omega < R_L < 65 \Omega$
7.1.35	CANH, CANL dominant output voltage difference $V_{diff} = V_{CANH} - V_{CANL}$	$V_{diff}$	1.5	–	3.0	V	$V_{TxD} = 0 \text{ V}$ ; $50 \Omega < R_L < 65 \Omega$
7.1.36	Driver Symmetry $V_{SYM} = V_{CANH} + V_{CANL}$	$V_{SYM}$	4.5	–	5.5	V	$V_{TxD} = 0 \text{ V}$ ; $V_{CC} = 5 \text{ V}$ $50 \Omega < R_L < 65 \Omega$
7.1.37	CANL short circuit current	$I_{CANLsc}$	50	100	200	mA	$V_{CANLshort} = 18 \text{ V}$
7.1.38	CANH short circuit current	$I_{CANHsc}$	-200	-100	-50	mA	$V_{CANHshort} = 0 \text{ V}$
7.1.39	Leakage current	$I_{CANHL,ik}$	-5	0	5	$\mu\text{A}$	$V_{CC} = 0 \text{ V}$ ; $V_{CANH} = V_{CANL}$ ; $0 \text{ V} < V_{CANH,L} < 5 \text{ V}$

**Table 6 Electrical Characteristics (cont'd)**

4.75 V <  $V_{CC}$  < 5.25 V;  $R_L = 60 \Omega$ ;  $T_j = -40 \text{ }^\circ\text{C}$  to  $+150 \text{ }^\circ\text{C}$ ; all voltages with respect to ground; positive current flowing into pin; unless otherwise specified.

Pos.	Parameter	Symbol	Limit Values			Unit	Remarks
			Min.	Typ.	Max.		
<b>Dynamic CAN-Transceiver Characteristics</b>							
7.1.40	Propagation delay TxD-to-RxD LOW ("Recessive" to "Dominant")	$t_{d(L),TR}$	–	–	255	ns	$C_L = 100 \text{ pF}$ ; $V_{CC} = 5 \text{ V}$ ; $C_{RxD} = 15 \text{ pF}$
7.1.41	Propagation delay TxD-to-RxD HIGH ("Dominant" to "Recessive")	$t_{d(H),TR}$	–	–	255	ns	$C_L = 100 \text{ pF}$ ; $V_{CC} = 5 \text{ V}$ ; $C_{RxD} = 15 \text{ pF}$
7.1.42	Propagation delay TxD LOW to bus "Dominant"	$t_{d(L),T}$	–	110	–	ns	$C_L = 100 \text{ pF}$ ; $V_{CC} = 5 \text{ V}$ ; $C_{RxD} = 15 \text{ pF}$
7.1.43	Propagation delay TxD HIGH to bus "Recessive"	$t_{d(H),T}$	–	110	–	ns	$C_L = 100 \text{ pF}$ ; $V_{CC} = 5 \text{ V}$ ; $C_{RxD} = 15 \text{ pF}$
7.1.44	Propagation delay bus "Dominant" to RxD "Low"	$t_{d(L),R}$	–	70	–	ns	$C_L = 100 \text{ pF}$ ; $V_{CC} = 5 \text{ V}$ ; $C_{RxD} = 15 \text{ pF}$
7.1.45	Propagation delay bus "Recessive" to RxD "High"	$t_{d(H),R}$	–	100	–	ns	$C_L = 100 \text{ pF}$ ; $V_{CC} = 5 \text{ V}$ ; $C_{RxD} = 15 \text{ pF}$
7.1.46	Time for mode change	$t_{Mode}$	–	–	10	$\mu\text{s}$	1)

1) Not subject to production test specified by design



7.2 Diagrams

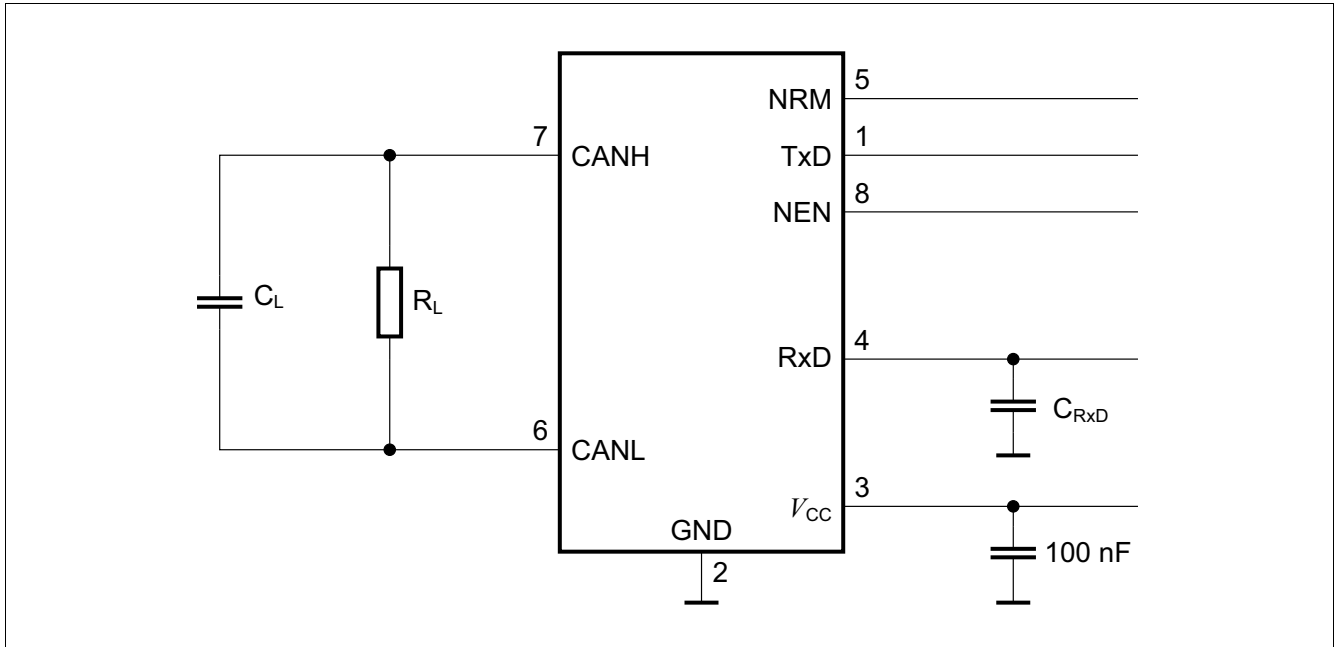


Figure 8 Simplified test circuit

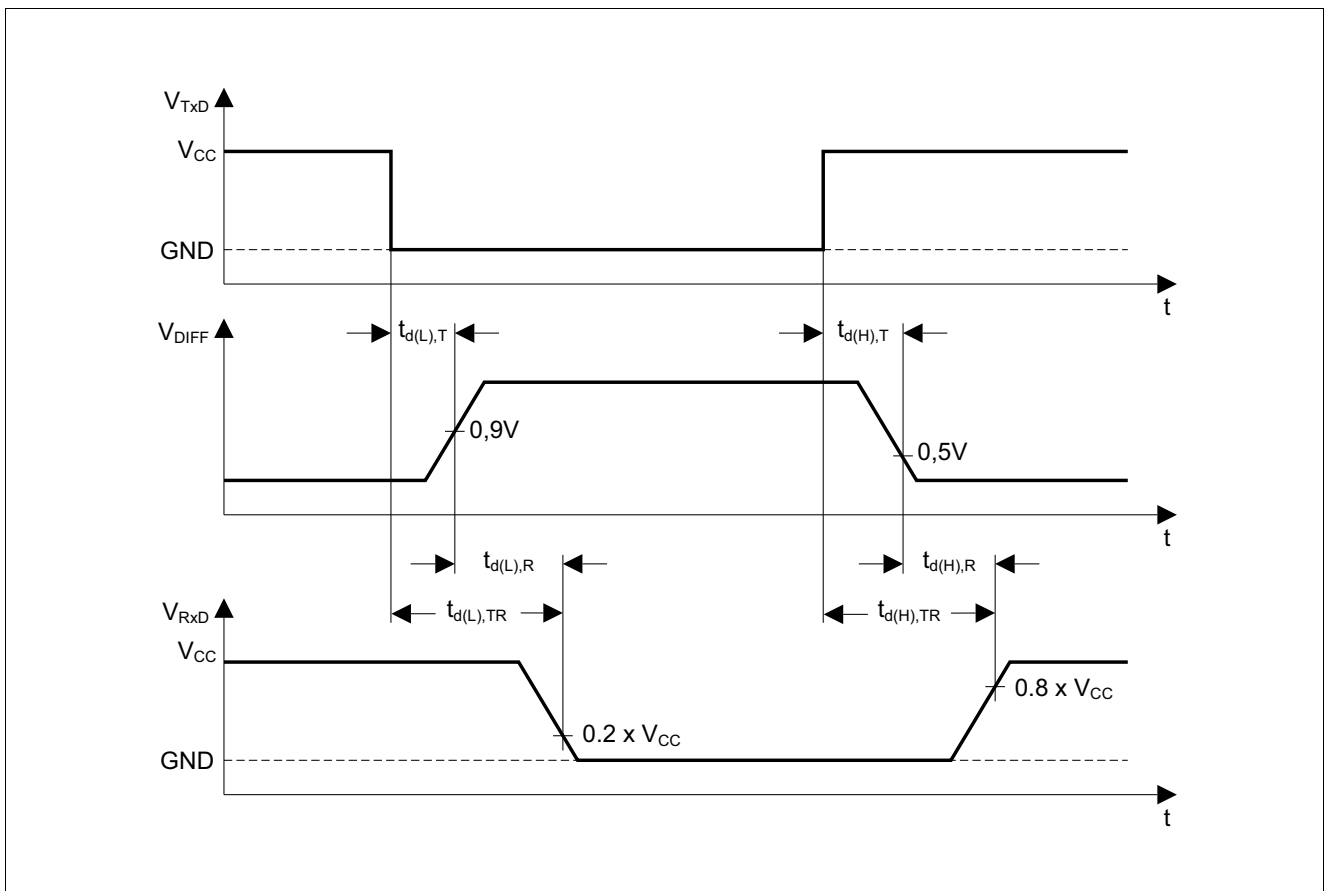


Figure 9 Timing diagram for dynamic characteristics

## 8 Application Information

### 8.1 Application Example

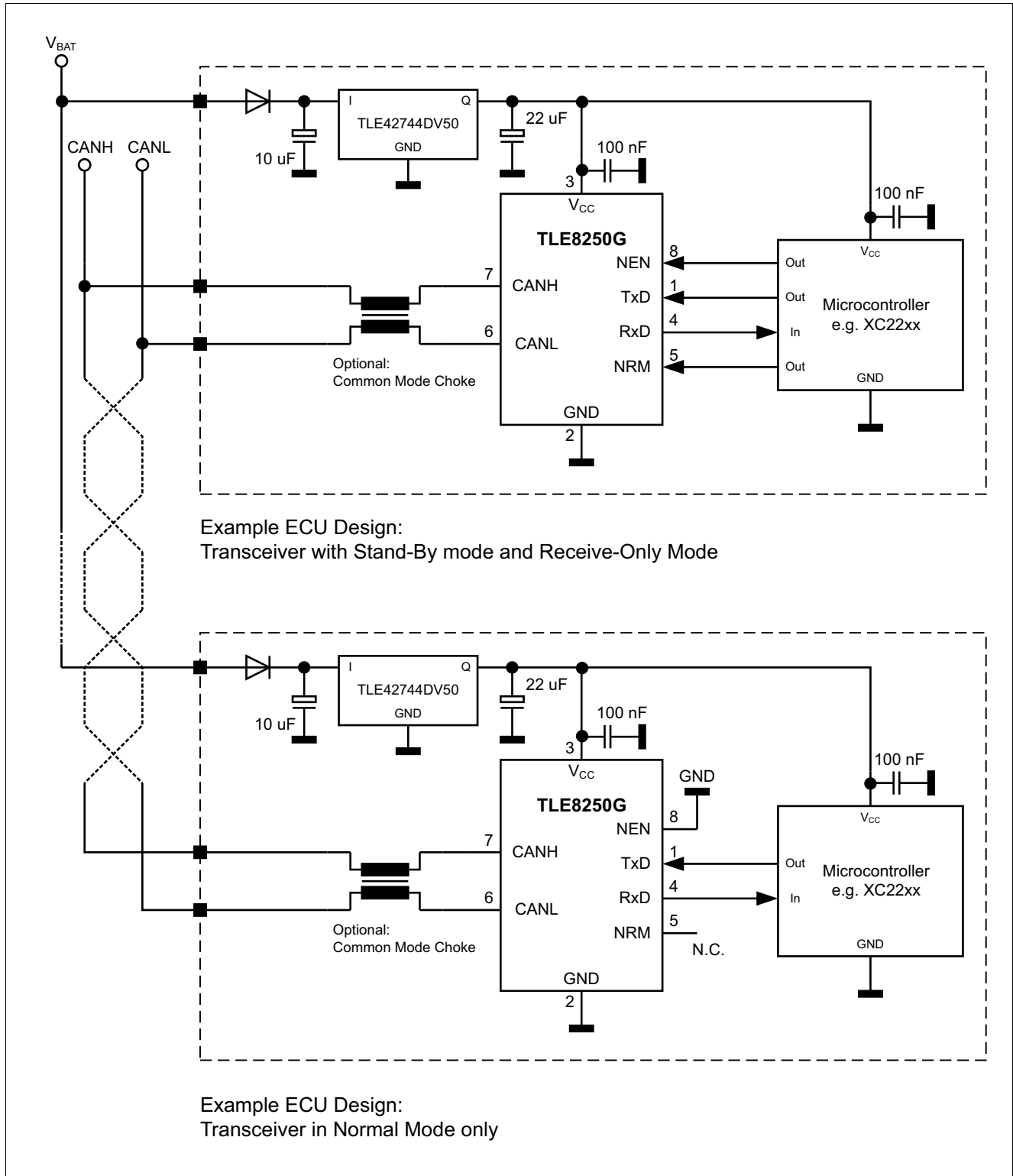


Figure 10 Simplified Application for the TLE8250G

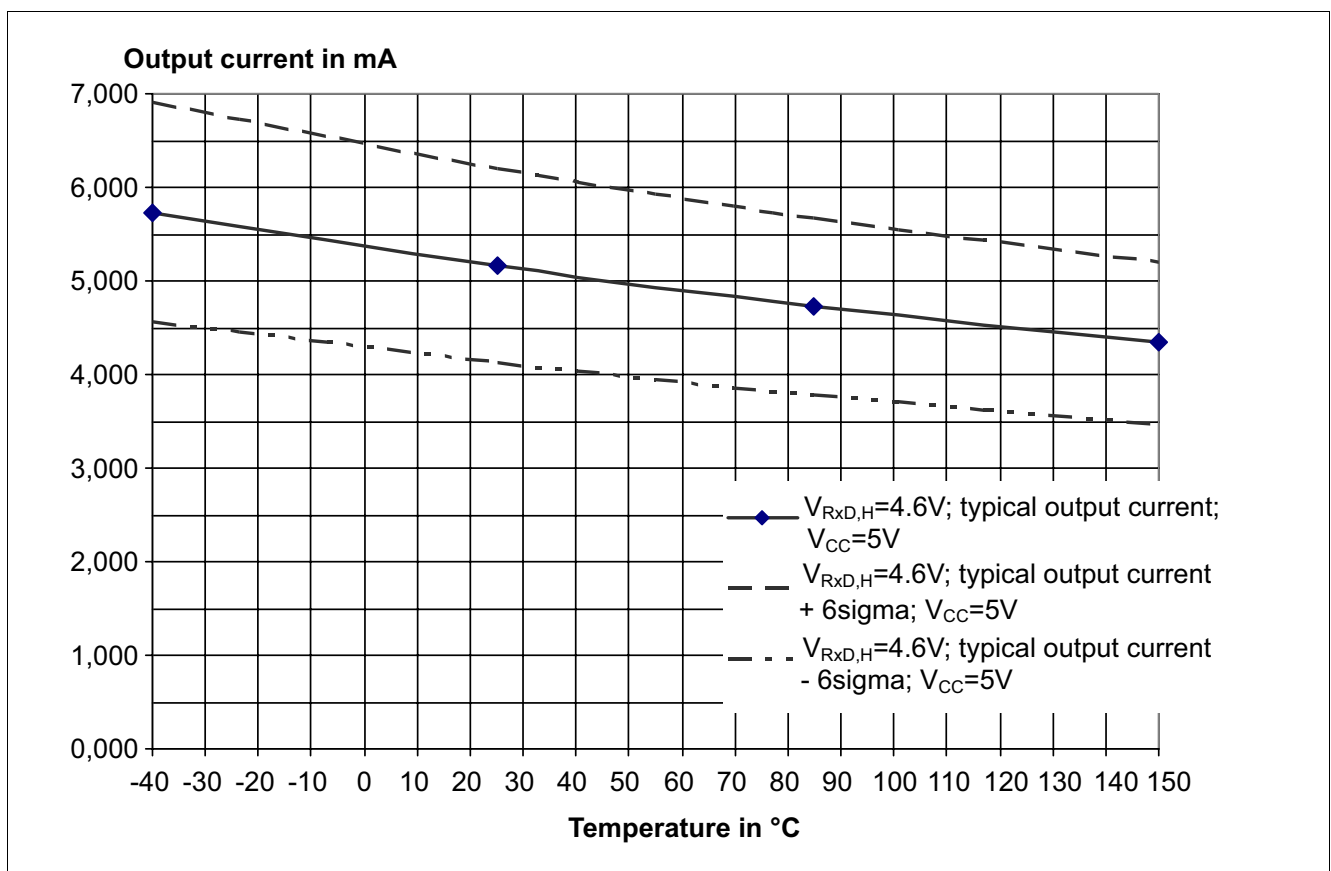
## 8.2 Output Characteristics of the RxD Pin

The RxD output pin is designed as a push-pull output stage (see [Figure 1](#)), meaning to produce a logical “Low” signal the TLE8250G switches the RxD output to GND. Vice versa to produce a logical “High” signal the TLE8250G switches the RxD output to  $V_{CC}$ .

The level  $V_{RxD,H}$  for a logical “High” signal on the RxD output depends on the load on the RxD output pin and therefore on the RxD output current  $I_{RD,H}$ . For a load against the GND potential, the current  $I_{RD,H}$  is flowing out of the RxD output pin.

Similar to the logical “High” signal, the level  $V_{RxD,L}$  for a logical “Low” signal on the RxD output pin depends on the input current  $I_{RD,L}$ . For a load against the power supply  $V_{CC}$  the current  $I_{RD,L}$  is flowing into the RxD output pin.

Currents flowing into the device are marked positive inside the data sheet and currents flowing out of the device TLE8250G are marked negative inside the data sheet (see [Table 6](#)).

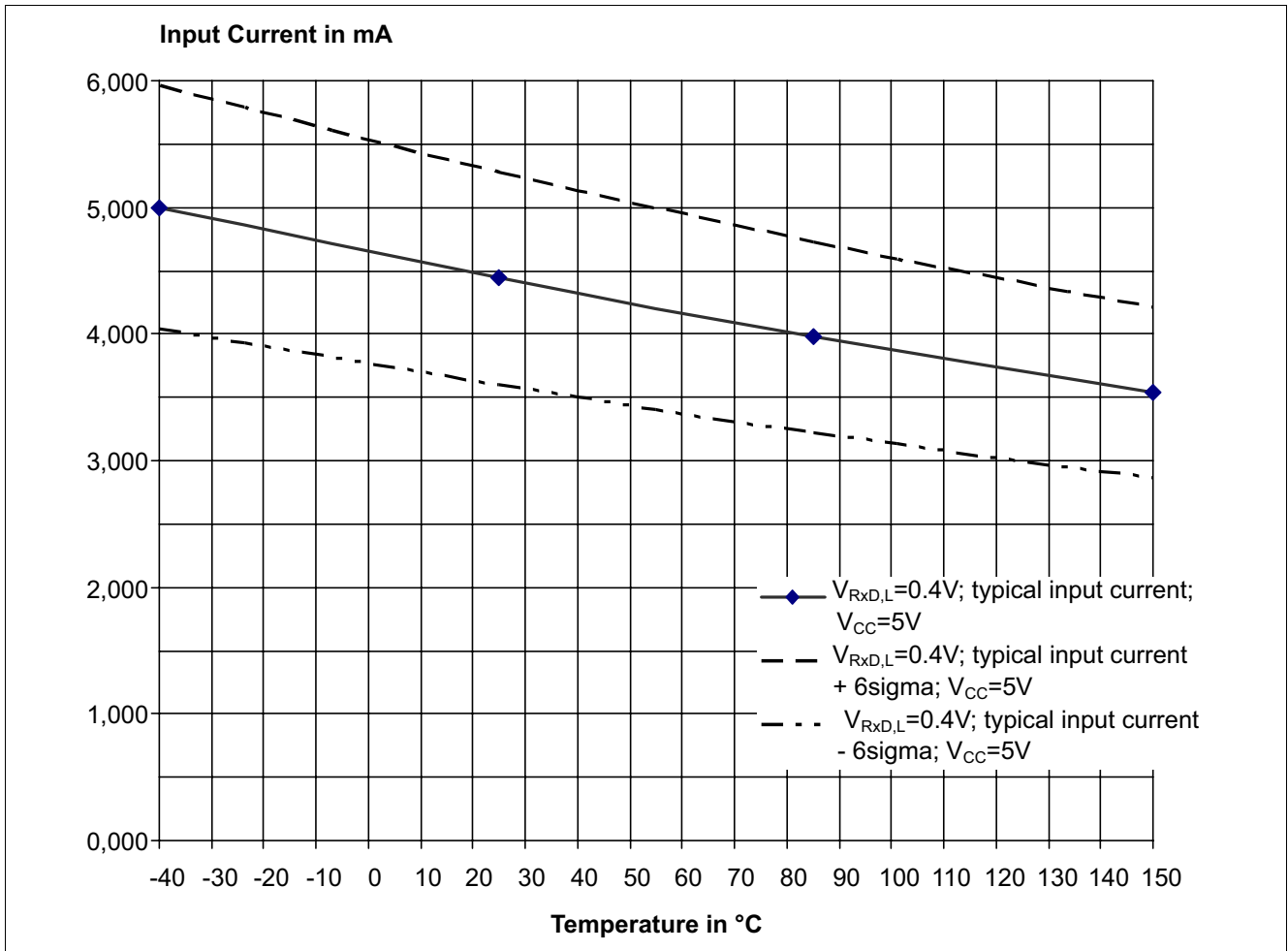


**Figure 11 RxD Output driver capability for a logical “High” signal<sup>1)</sup>**

The diagram in [Figure 11](#) shows the output current capability of the RxD output pin depended on the chip temperature  $T_J$ . At a logical “High” signal  $V_{RxD,H} = 4.6 V$ , the typical output current is between 5.7 mA for  $-40\text{ °C}$  and 4.7 mA for a temperature of  $+150\text{ °C}$ . The dependency of the output current on the temperature is almost linear. The upper curve “ $V_{RxD,H} = 4.6 V$ ; typical output current + 6 sigma;  $V_{CC} = 5 V$ ” reflects the expected maximum value of the RxD output current of the TLE8250G.

The lower curve “ $V_{RxD,H} = 4.6 V$ ; typical output current - 6 sigma;  $V_{CC} = 5 V$ ” reflects the expected minimum value of the RxD output current of the TLE8250G. All simulations are based on a power supply  $V_{CC} = 5.0 V$ .

1) Characteristics generated by simulation and specified by design. Production test criteria is described in [Table 6](#); Pos.: 7.1.8



**Figure 12 RxD Output driver capability for a logical “Low” signal<sup>1)</sup>**

The diagram in **Figure 12** shows the input current capability of the RxD output pin depended on the chip temperature  $T_J$ . At a logical “Low” signal  $V_{RxD,L} = 0.4\text{ V}$ , the typical output current is between 5 mA for  $-40\text{ °C}$  and 3.5 mA for a temperature of  $+150\text{ °C}$ . The dependency of the input current on the temperature is almost linear. The upper curve “ $V_{RxD,L} = 0.4\text{ V}$ ; typical input current + 6 sigma;  $V_{CC}=5\text{ V}$ ” reflects the expected maximum value of the RxD output current of the TLE8250G.

The lower curve “ $V_{RxD,L} = 0.4\text{ V}$ ; typical input current - 6 sigma;  $V_{CC}=5\text{ V}$ ” reflects the expected minimum value of the RxD output current of the TLE8250G. All simulations are based on a power supply  $V_{CC} = 5.0\text{ V}$ .

### 8.3 Further Application Information

- Please contact us for information regarding the FMEA pin.
- Existing App. Note (Title)
- For further information you may contact <http://www.infineon.com/transceiver>

1) Characteristics generated by simulation and specified by design. Production test criteria is described in **Table 6**; Pos.: 7.1.9

## 9 Package Outlines

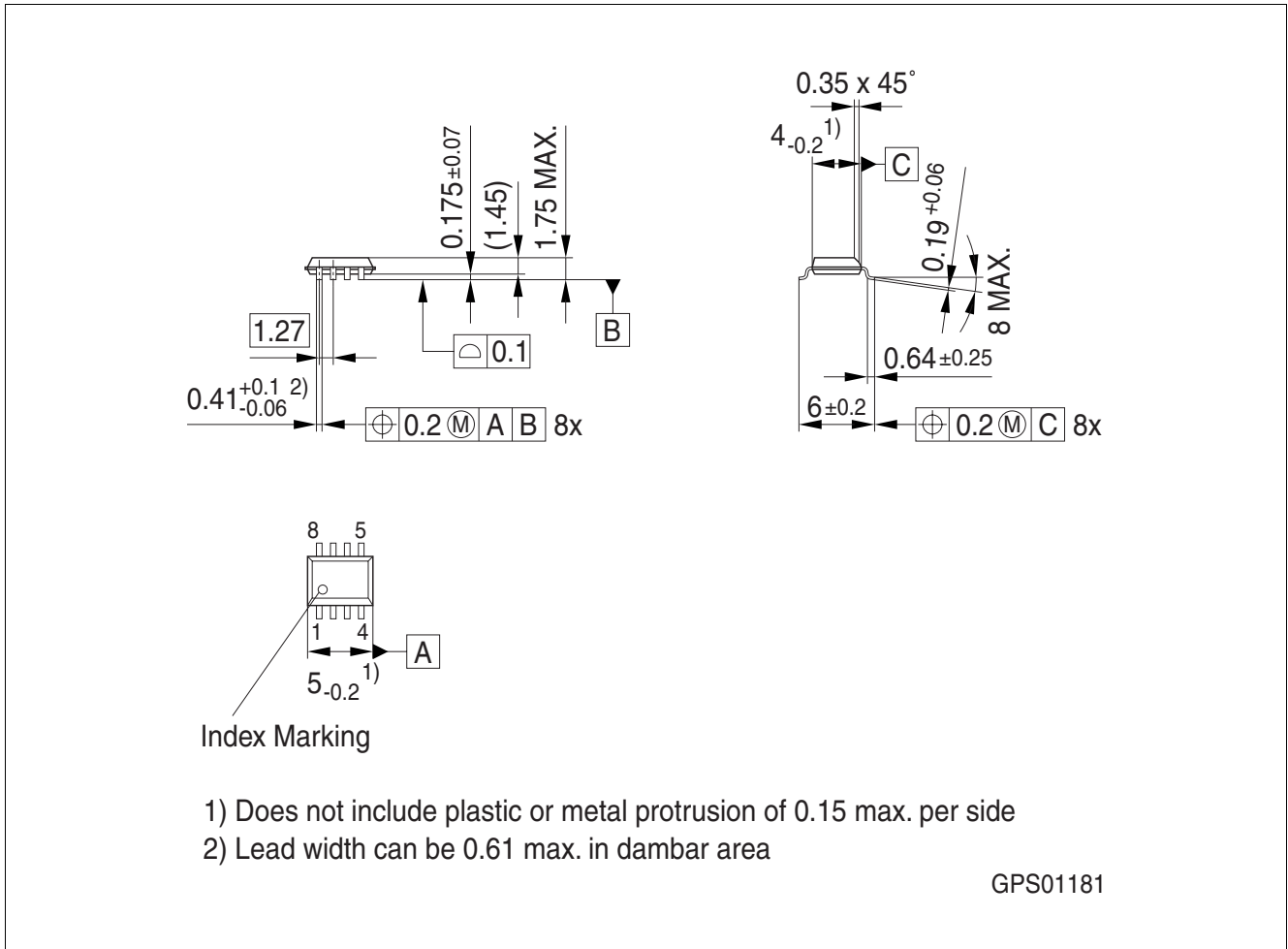


Figure 13 PG-DSO-8 (Plastic Dual Small Outline PG-DSO-8-16)

### Green Product (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e. Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

## 10 Revision History

Revision	Date	Changes
1.0	2010-06-02	Data Sheet Created

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